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### 1. Global joint venture starts operations as WeEn Semiconductors

Dear customer.

As from November 9th, 2015 NXP Semiconductors N.V. and Beijing JianGuang Asset Management Co. Ltd established Bipolar Power joint venture (JV), **WeEn Semiconductors**, which will be used in future Bipolar Power documents together with new contact details.

In this document where the previous NXP references remain, please use the new links as shown below.

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Thank you for your cooperation and understanding,

WeEn Semiconductors





## 1. General description

Planar passivated Silicon Controlled Rectifier with sensitive gate in a SOT54 (TO-92) plastic package. This SCR is designed to be interfaced directly to microcontrollers, logic ICs and other low power gate trigger circuits.

### 2. Features and benefits

- · High voltage capability
- Planar passivated for voltage ruggedness and reliability
- Sensitive gate

## 3. Applications

- Ignition circuits
- Lighting ballasts
- Protection circuits
- Switched Mode Power Supplies

## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit	
$V_{DRM}$	repetitive peak off- state voltage			-	-	600	V	
$V_{RRM}$	repetitive peak reverse voltage			-	-	600	V	
I <sub>TSM</sub>	non-repetitive peak on- state current	half sine wave; $T_{j(init)}$ = 25 °C; $t_p$ = 10 ms; Fig. 4; Fig. 5		-	-	8	Α	
		half sine wave; $T_{j(init)} = 25 \text{ °C}$ ; $t_p = 8.3 \text{ ms}$		-	-	9	А	
Tj	junction temperature			-	-	125	°C	
I <sub>T(AV)</sub>	average on-state current	half sine wave; T <sub>lead</sub> ≤ 83 °C; <u>Fig. 1</u>		_	-	0.5	Α	
I <sub>T(RMS)</sub>	RMS on-state current	half sine wave; $T_{lead} \le 83$ °C; Fig. 2; Fig. 3		-	-	0.8	Α	
Static characteristics								
I <sub>GT</sub>	gate trigger current	$V_D = 12 \text{ V}; I_T = 10 \text{ mA}; T_j = 25 \text{ °C};$ Fig. 7		-	50	200	μΑ	
Dynamic chara	Dynamic characteristics							

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Symbol	Parameter	Conditions	Min	Тур	Max	Unit
dV <sub>D</sub> /dt	rate of rise of off-state voltage	$V_{DM}$ = 402 V; $T_j$ = 125 °C; $R_{GK}$ = 1 kΩ; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; Fig. 12	500	800	-	V/µs

# 5. Pinning information

#### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	Α	anode		А <del>-    </del> К
2	G	gate		G sym037
3	К	cathode	321 TO 22 (SOTEA)	Symost
			TO-92 (SOT54)	

# 6. Ordering information

### **Table 3. Ordering information**

Type number	Package					
	Name	Description	Version			
BT169G	TO-92	plastic single-ended leaded (through hole) package; 3 leads	SOT54			

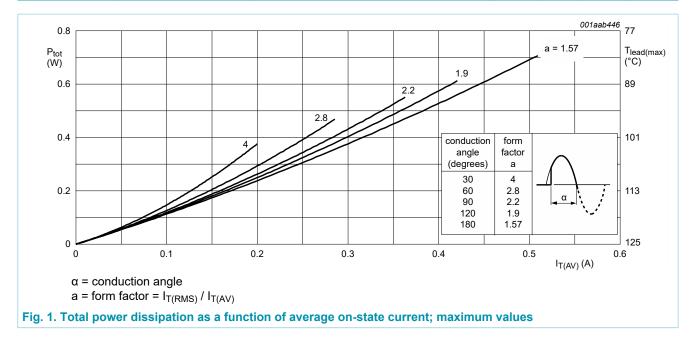
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# 7. Limiting values

**Table 4. Limiting values** 

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage		-	600	V
$V_{RRM}$	repetitive peak reverse voltage		-	600	V
I <sub>T(AV)</sub>	average on-state current	half sine wave; T <sub>lead</sub> ≤ 83 °C; <u>Fig. 1</u>	-	0.5	Α
I <sub>T(RMS)</sub>	RMS on-state current	half sine wave; T <sub>lead</sub> ≤ 83 °C; <u>Fig. 2</u> ; <u>Fig. 3</u>	-	0.8	Α
I <sub>TSM</sub>	non-repetitive peak on- state current	half sine wave; $T_{j(init)}$ = 25 °C; $t_p$ = 10 ms; Fig. 4; Fig. 5	-	8	А
		half sine wave; T <sub>j(init)</sub> = 25 °C; t <sub>p</sub> = 8.3 ms	-	9	Α
I <sup>2</sup> t	I <sup>2</sup> t for fusing	$t_p$ = 10 ms; SIN	-	0.32	A²s
dl <sub>T</sub> /dt	rate of rise of on-state current	$I_T = 2 \text{ A}$ ; $I_G = 10 \text{ mA}$ ; $dI_G/dt = 100 \text{ mA/}\mu\text{s}$	-	50	A/µs
I <sub>GM</sub>	peak gate current		-	1	Α
$V_{RGM}$	peak reverse gate voltage		-	5	V
P <sub>GM</sub>	peak gate power		-	2	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	0.1	W
T <sub>stg</sub>	storage temperature		-40	150	°C
T <sub>j</sub>	junction temperature		-	125	°C



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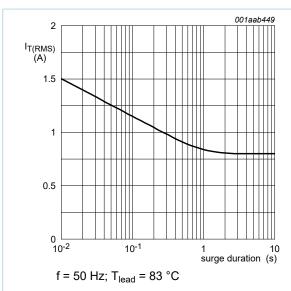


Fig. 2. RMS on-state current as a function of surge duration for sinusoidal currents

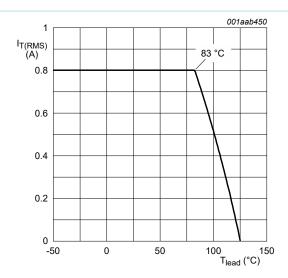


Fig. 3. RMS on-state current as a function of lead temperature; maximum values

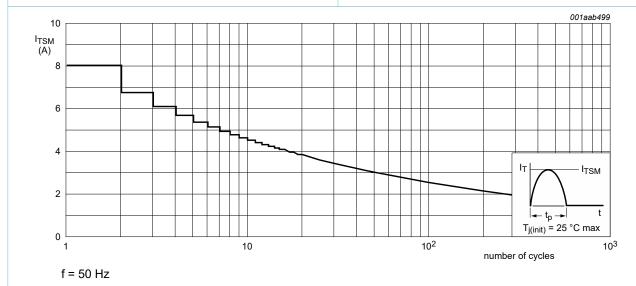
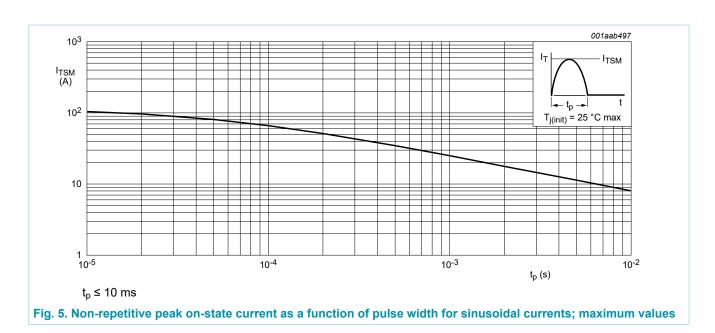


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

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### 8. Thermal characteristics

**Table 5. Thermal characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-lead)</sub>	thermal resistance from junction to lead	<u>Fig. 6</u>	-	-	60	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient free air	printed circuit board mounted: lead length = 4 mm	-	150	-	K/W

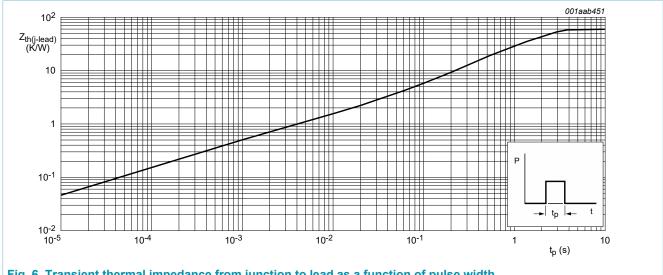


Fig. 6. Transient thermal impedance from junction to lead as a function of pulse width

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## 9. Characteristics

#### **Table 6. Characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static char	acteristics	1				
I <sub>GT</sub>	gate trigger current	$V_D = 12 \text{ V}; I_T = 10 \text{ mA}; T_j = 25 ^{\circ}\text{C};$ Fig. 7	-	50	200	μA
lL	latching current	$V_D = 12 \text{ V}; I_G = 0.5 \text{ mA}; T_j = 25 \text{ °C};$ Fig. 8	-	2	6	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>	-	2	5	mA
$V_{T}$	on-state voltage	I <sub>T</sub> = 1.2 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>	-	1.25	1.7	V
$V_{GT}$	gate trigger voltage	$V_D = 12 \text{ V}; I_T = 10 \text{ mA}; T_j = 25 ^C;$ Fig. 11	-	0.5	0.8	V
		$V_D = 600 \text{ V}; I_T = 10 \text{ mA}; T_j = 125 \text{ °C};$ Fig. 11	0.2	0.3	-	V
I <sub>D</sub>	off-state current	$V_D = 600 \text{ V}; R_{GK(ext)} = 1 \text{ k}\Omega; T_j = 125 °C$	-	0.05	0.1	mA
I <sub>R</sub>	reverse current	$V_R = 600 \text{ V}; T_j = 125 \text{ °C}; R_{GK(ext)} = 1 \text{ k}\Omega$	-	0.05	0.1	mA
Dynamic cl	haracteristics					
dV <sub>D</sub> /dt	rate of rise of off-state voltage	$V_{DM}$ = 402 V; $T_j$ = 125 °C; $R_{GK}$ = 1 k $\Omega$ ; $(V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; Fig. 12	500	800	-	V/µs
		$V_{DM}$ = 402 V; $T_j$ = 125 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit; Fig. 12	-	25	-	V/µs
t <sub>gt</sub>	gate-controlled turn-on time	$I_{TM}$ = 2 A; $V_D$ = 600 V; $I_G$ = 10 mA; $dI_G/$ dt = 0.1 A/µs; $T_j$ = 25 °C	-	2	-	μs
t <sub>q</sub>	commutated turn-off time	$V_{DM}$ = 402 V; $T_j$ = 125 °C; $I_{TM}$ = 1.6 A; $V_R$ = 35 V; $(dI_T/dt)_M$ = 30 A/ $\mu$ s; $dV_D/dt$ = 2 V/ $\mu$ s; $R_{GK(ext)}$ = 1 k $\Omega$ ; $(V_{DM}$ = 67% of $V_{DRM})$	-	100	-	μs

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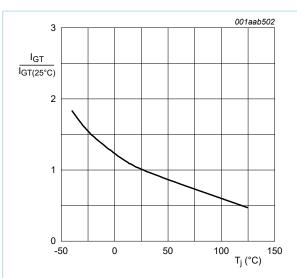


Fig. 7. Normalized gate trigger current as a function of junction temperature

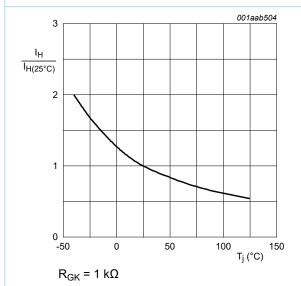


Fig. 9. Normalized holding current as a function of junction temperature

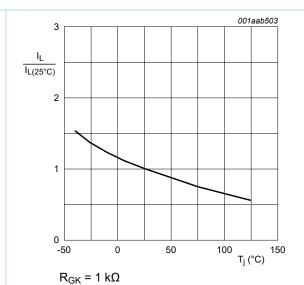
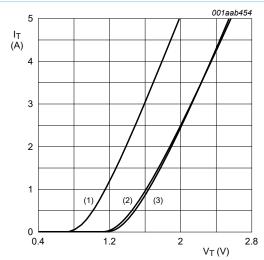


Fig. 8. Normalized latching current as a function of junction temperature



 $V_o$  = 1.067 V;  $R_s$  = 0.187  $\Omega$ 

(1) T<sub>i</sub> = 125 °C; typical values

(2) T<sub>j</sub> = 125 °C; maximum values (3) T<sub>j</sub> = 25 °C; maximum values

Fig. 10. On-state current as a function of on-state voltage

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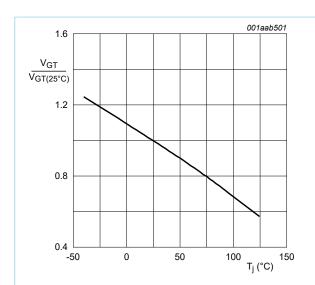


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

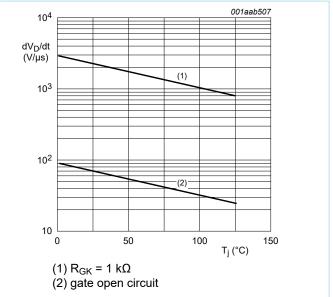


Fig. 12. Critical rate of rise of off-state voltage as a function of junction temperature; typical values

# 10. Package outline

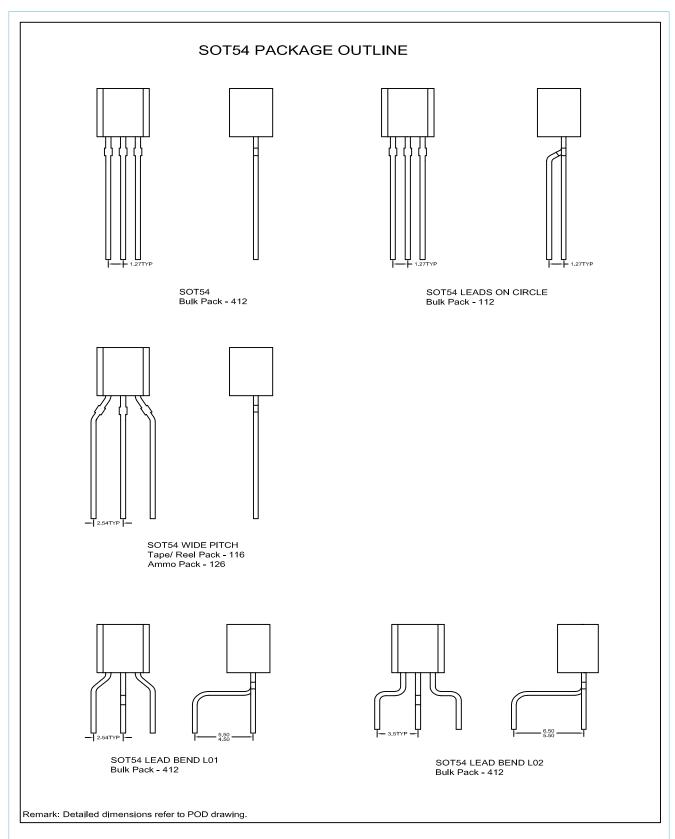


Fig. 13. Package outline TO-92 (SOT54)

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## 11. Legal information

#### **Data sheet status**

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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